

ABSTRACT

DIVIDING METHOD AND DIVIDING DEVICE OF BRITTLE MATERIAL SUBSTRATE

To hold a brittle material substrate on a dicing ring and prevent occurrence of a curved portion at a time of placing the substrate on a table. A sapphire substrate (30) is held on an adhesive tape (32) that is affixed to a dicing ring (31). An elastic support plate (40) is provided on a glass table (12) of a dividing device, and the dicing ring (31) is fixed thereabove. A roller (22) is pressed onto the sapphire substrate (30) and is relatively moved, so that the sapphire substrate (30) is thereby closely adhered onto the elastic support plate (40). Then, a scribe line is confirmed using a monitor camera and a break bar is lowered from just above the scribe line to thereby separate the brittle material substrate.

(Figure 4)